ISL23318

Single, 128-taps Low Voltage Digitally Controlled Potentiometer (XDCP™)

The ISL23318 is a volatile, low voltage, low noise, low power, I²C Bus™, 128 Taps, single digitally controlled potentiometer (DCP), which integrates DCP core, wiper switches and control logic on a monolithic CMOS integrated circuit.

The digitally controlled potentiometer is implemented with a combination of resistor elements and CMOS switches. The position of the wipers are controlled by the user through the I²C bus interface. The potentiometer has an associated volatile Wiper Register (WR) that can be directly written to and read by the user. The contents of the WR controls the position of the wiper. When powered on, the ISL23318's wiper always commences at mid-scale (64 tap position).

The low voltage, low power consumption, and small package of the ISL23318 make it an ideal choice for use in battery operated equipment. In addition, the ISL23318 has a V_{LOGIC} pin allowing down to 1.2V bus operation, independent from the V_{CC} value. This allows for low logic levels to be connected directly to the ISL23318 without passing through a voltage level shifter.

The DCP can be used as a three-terminal potentiometer or as a two-terminal variable resistor in a wide variety of applications including control, parameter adjustments, and signal processing.

Features

- 128 resistor taps
- I²C serial interface
  - No additional level translator for low bus supply
  - Two address pins allow up to four devices per bus
- Power supply
  - V_{CC} = 1.7V to 5.5V analog power supply
  - V_{LOGIC} = 1.2V to 5.5V I²C bus/logic power supply
- Wiper resistance: 70Ω typical at V_{CC} = 3.3V
- Shutdown Mode - forces the DCP into an end-to-end open circuit and R_W is shorted to R_L internally
- Power-on preset to mid-scale (64 tap position)
- Shutdown and standby current <2.8µA max
- DCP terminal voltage from 0V to V_{CC}
- 10kΩ or 100kΩ total resistance
- Extended industrial temperature range: -40°C to +125°C
- 10 Ld MSOP or 10 Ld UTQFN packages
- Pb-free (RoHS compliant)

Applications

- Gain adjustment in battery powered instruments
- Trimming sensor circuits
- Power supply margining
- RF power amplifier bias compensation

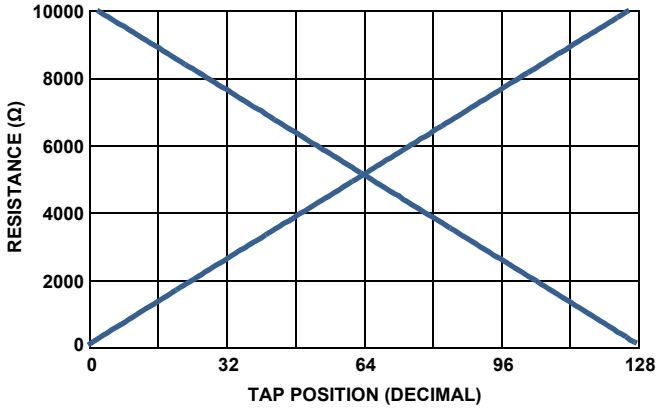


FIGURE 1. FORWARD AND BACKWARD RESISTANCE vs TAP POSITION, 10k DCP

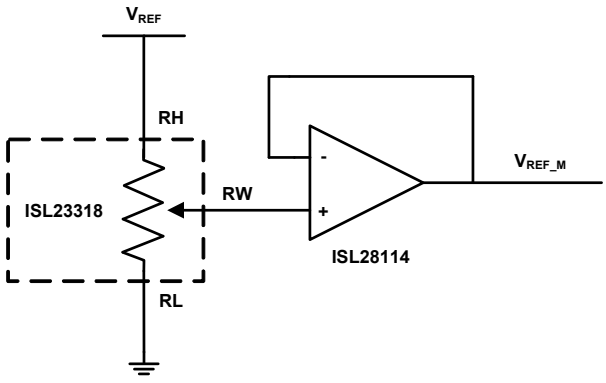
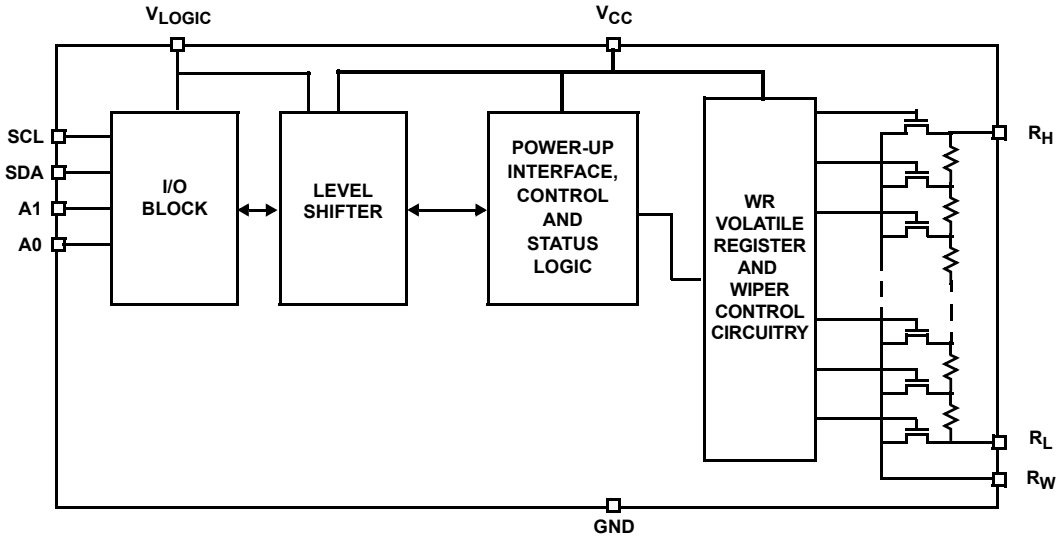


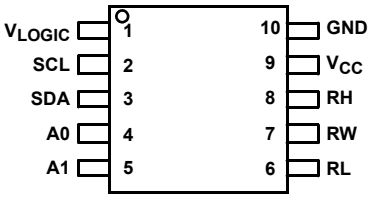
FIGURE 2. V_{REF} ADJUSTMENT

Block Diagram

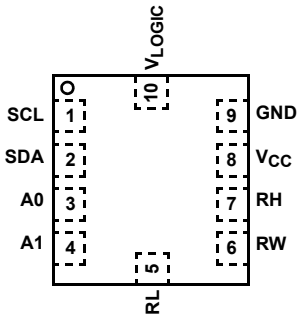


Pin Configurations

ISL23318
(10 LD MSOP)
TOP VIEW



ISL23318
(10 LD UTQFN)
TOP VIEW



Pin Descriptions

MSOP	UTQFN	SYMBOL	DESCRIPTION
1	10	V_{LOGIC}	I^2C bus /logic supply. Range 1.2V to 5.5V
2	1	SCL	Logic Pin - Serial bus clock input
3	2	SDA	Logic Pin - Serial bus data input/open drain output
4	3	A0	Logic Pin - Hardwire slave address pin for I^2C serial bus. Range: V_{LOGIC} or GND
5	4	A1	Logic Pin - Hardwire slave address pin for I^2C serial bus. Range: V_{LOGIC} or GND
6	5	RL	DCP low terminal
7	6	RW	DCP wiper terminal
8	7	RH	DCP high terminal
9	8	V_{CC}	Analog power supply. Range 1.7V to 5.5V
10	9	GND	Ground pin

Ordering Information

PART NUMBER (Note 4)	PART MARKING	RESISTANCE OPTION (kΩ)	PACKAGE (RoHS Compliant)	PKG. DWG. #	CARRIER TYPE (Note 1)	TEMP RANGE
ISL23318TFUZ (Note 2)	3318T	100	10 Ld MSOP	M10.118	Tube	-40 to +125°C
ISL23318TFUZ-TK (Note 2)					Reel, 1k	
ISL23318WFRUZ-T7A (Note 3)	HF	10	10 Ld 2.1x1.6 UTQFN	L10.2.1x1.6A	Reel, 250	
ISL23318WFRUZ-TK (Note 3)					Reel, 1k	

NOTES:

1. Please refer to TB347 for details on reel specifications.
2. These Pb-free plastic packaged products employ special Pb-free material sets, molding compounds/die attach materials, and 100% matte tin plate plus anneal (e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations). Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J-STD-020.
3. These Pb-free plastic packaged products employ special Pb-free material sets; molding compounds/die attach materials and NiPdAu plate-e4 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J-STD-020.
4. For Moisture Sensitivity Level (MSL), please see device information page for ISL23318. For more information on MSL please see TB363.

Absolute Maximum Ratings

Supply Voltage Range
V_{CC} ..... -0.3V to 6.0V
V_{LOGIC} ..... -0.3V to 6.0V
Voltage on Any DCP Terminal Pin ..... -0.3V to 6.0V
Voltage on Any Digital Pins ..... -0.3V to 6.0V
Wiper current I_W (10s) ..... ±6mA
ESD Rating
Human Body Model (Tested per JESD22-A114E) 6.5kV
CDM Model (Tested per JESD22-A114E) 1kV
Machine Model (Tested per JESD22-A115-A) 200V
Latch Up (Tested per JESD-78B; Class 2, Level A) .... 100mA @ +125°C

Thermal Information

Thermal Resistance (Typical)	θ_{JA} (°C/W)	θ_{JC} (°C/W)
10 Ld MSOP Package (Notes 5, 6)	170	70
10 Ld UTQFN Package (Notes 5, 6)	145	90

Maximum Junction Temperature (Plastic Package) ..... +150°C
Storage Temperature Range ..... -65°C to +150°C
Pb-Free Reflow Profile ..... see TB493

Recommended Operating Conditions

Temperature ..... -40°C to +125°C
V_{CC} Supply Voltage ..... 1.7V to 5.5V
V_{LOGIC} Supply Voltage ..... 1.2V to 5.5V
DCP Terminal Voltage ..... 0 to V_{CC}
Max Wiper Current ..... ±3mA

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

NOTES:

5. θ_{JA} is measured with the component mounted on a high effective thermal conductivity test board in free air. See TB379 for details.
6. For θ_{JC}, the "case temp" location is the center top of the package.

Analog Specifications

V_{CC} = 2.7V to 5.5V, V_{LOGIC} = 1.2V to 5.5V over recommended operating conditions unless otherwise stated.
Boldface limits apply over the operating temperature range, -40°C to +125°C.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN (Note 19)	TYP (Note 7)	MAX (Note 19)	UNIT
R_{TOTAL}	R_H to R_L Resistance	W option	-	10	-	kΩ
		T option	-	100	-	kΩ
	R_H to R_L Resistance Tolerance	-	**-20**	±2	**+20**	%
	End-to-End Temperature Coefficient	W option	-	175	-	ppm/°C
		T option	-	70	-	ppm/°C
V_{RH}, V_{RL}	DCP Terminal Voltage	V_{RH} or V_{RL} to GND	**0**	-	**V_{CC}**	V
R_W	Wiper Resistance	R_H - floating, V_{RL} = 0V, force I_W current to the wiper, $I_W = (V_{CC} - V_{RL})/R_{TOTAL}$, V_{CC} = 2.7V to 5.5V	-	70	**200**	Ω
		V_{CC} = 1.7V	-	580	-	Ω
$C_H/C_L/C_W$	Terminal Capacitance	See "DCP Macro Model" on page 8	-	32	-	pF
I_{LkgDCP}	Leakage on DCP Pins	Voltage at pin from GND to V_{CC}	**-0.4**	<0.1	**0.4**	µA
Noise	Resistor Noise Density	Wiper at middle point, W option	-	16	-	nV/√Hz
		Wiper at middle point, T option	-	61	-	nV/√Hz
Feed Thru	Digital Feed-Through from Bus to Wiper	Wiper at middle point	-	-65	-	dB
PSRR	Power Supply Reject Ratio	Wiper output change if V_{CC} change ±10%; wiper at middle point	-	-75	-	dB

Analog Specifications

V_{CC} = 2.7V to 5.5V, V_{LOGIC} = 1.2V to 5.5V over recommended operating conditions unless otherwise stated. **Boldface limits apply over the operating temperature range, -40°C to +125°C. (Continued)**

SYMBOL	PARAMETER	TEST CONDITIONS	MIN (Note 19)	TYP (Note 7)	MAX (Note 19)	UNIT
VOLTAGE DIVIDER MODE (0V @ RL; V_{CC} @ RH; measured at RW, unloaded)						
INL (Note 12)	Integral Non-linearity, Guaranteed Monotonic	W, T options	**-0.5**	±0.15	**+0.5**	LSB (Note 8)
DNL (Note 11)	Differential Non-linearity, Guaranteed Monotonic	W, T options	**-0.5**	±0.15	**+0.5**	LSB (Note 8)
FSerror (Note 10)	Full-scale Error	W option	**-2.5**	-1.5	**0**	LSB (Note 8)
		T option	**-1.0**	-0.7	**0**	LSB (Note 8)
ZSerror (Note 9)	Zero-scale Error	W option	**0**	1.5	**2.5**	LSB (Note 8)
		T option	**0**	0.7	**1.0**	LSB (Note 8)
TC_V (Notes 13)	Ratiometric Temperature Coefficient	W option, Wiper Register set to 40 hex	-	8	-	ppm/°C
		T option, Wiper Register set to 40 hex	-	2.3	-	ppm/°C
	Large Signal Wiper Settling Time	From code 0 to 7F hex	-	300	-	ns
f_{cutoff}	-3dB Cutoff Frequency	Wiper at middle point W option	-	1200	-	kHz
		Wiper at middle point T option	-	120	-	kHz
RHEOSTAT MODE (Measurements between RW and RL pins with RH not connected, or between RW and RH with RL not connected)						
R_{INL} (Note 17)	Integral Non-linearity, Guaranteed Monotonic	W option; V_{CC} = 2.7V to 5.5V	**-1.0**	±0.5	**+1.0**	MI (Note 14)
		W option; V_{CC} = 1.7V	-	±3.0	-	MI (Note 14)
		T option; V_{CC} = 2.7V to 5.5V	**-0.5**	±0.15	**+0.5**	MI (Note 14)
		T option; V_{CC} = 1.7V	-	±1.0	-	MI (Note 14)
R_{DNL} (Note 16)	Differential Non-linearity, Guaranteed Monotonic	W option; V_{CC} = 2.7V to 5.5V	**-0.5**	±0.15	**+0.5**	MI (Note 14)
		W option; V_{CC} = 1.7V	-	±0.4	-	MI (Note 14)
		T option; V_{CC} = 2.7V to 5.5V	**-0.5**	±0.15	**+0.5**	MI (Note 14)
		T option; V_{CC} = 1.7V	-	±0.4	-	MI (Note 14)
R_{offset} (Note 15)	Offset, Wiper at 0 Position	W option; V_{CC} = 2.7V to 5.5V	**0**	1.8	**3.0**	MI (Note 14)
		W option; V_{CC} = 1.7V	-	3.0	-	MI (Note 14)
		T option; V_{CC} = 2.7V to 5.5V	**0**	0.3	**1**	MI (Note 14)
		T option; V_{CC} = 1.7V	-	0.5	-	MI (Note 14)

Analog Specifications

V_{CC} = 2.7V to 5.5V, V_{LOGIC} = 1.2V to 5.5V over recommended operating conditions unless otherwise stated. **Boldface limits apply over the operating temperature range, -40°C to +125°C. (Continued)**

SYMBOL	PARAMETER	TEST CONDITIONS	MIN (Note 19)	TYP (Note 7)	MAX (Note 19)	UNIT
TCR (Note 18)	Resistance Temperature Coefficient	W option; Wiper register set between 19 hex and 7F hex	-	220	-	ppm/°C
		T option; Wiper register set between 19 hex and 7F hex	-	75	-	ppm/°C

Operating Specifications

V_{CC} = 2.7V to 5.5V, V_{LOGIC} = 1.2V to 5.5V over recommended operating conditions unless otherwise stated. **Boldface limits apply over the operating temperature range, -40°C to +125°C.**

SYMBOL	PARAMETER	TEST CONDITIONS	MIN (Note 19)	TYP (Note 7)	MAX (Note 19)	UNIT
I_{LOGIC}	V_{LOGIC} Supply Current (Write/Read)	V_{LOGIC} = 5.5V, V_{CC} = 5.5V, f_{SCL} = 400kHz (for I^2C active read and write)	-	-	**200**	µA
		V_{LOGIC} = 1.2V, V_{CC} = 1.7V, f_{SCL} = 400kHz (for I^2C active read and write)	-	-	**5**	µA
I_{CC}	V_{CC} Supply Current (Write/Read)	V_{LOGIC} = 5.5V, V_{CC} = 5.5V	-	-	**18**	µA
		V_{LOGIC} = 1.2V, V_{CC} = 1.7V	-	-	**10**	µA
$I_{LOGIC\ SB}$	V_{LOGIC} Standby Current	V_{LOGIC} = V_{CC} = 5.5V, I^2C interface in standby	-	-	**1.3**	µA
		V_{LOGIC} = 1.2V, V_{CC} = 1.7V, I^2C interface in standby	-	-	**0.4**	µA
$I_{CC\ SB}$	V_{CC} Standby Current	V_{LOGIC} = V_{CC} = 5.5V, I^2C interface in standby	-	-	**1.5**	µA
		V_{LOGIC} = 1.2V, V_{CC} = 1.7V, I^2C interface in standby	-	-	**1**	µA
$I_{LOGIC\ SHDN}$	V_{LOGIC} Shutdown Current	V_{LOGIC} = V_{CC} = 5.5V, I^2C interface in standby	-	-	**1.3**	µA
		V_{LOGIC} = 1.2V, V_{CC} = 1.7V, I^2C interface in standby	-	-	**0.4**	µA
$I_{CC\ SHDN}$	V_{CC} Shutdown Current	V_{LOGIC} = V_{CC} = 5.5V, I^2C interface in standby	-	-	**1.5**	µA
		V_{LOGIC} = 1.2V, V_{CC} = 1.7V, I^2C interface in standby			**1**	µA
I_{LkgDig}	Leakage Current, at Pins A0, A1, SDA, SCL	Voltage at pin from GND to V_{LOGIC}	**-0.4**	<0.1	**0.4**	µA
t_{DCP}	Wiper Response Time	SCL rising edge of the acknowledge bit after data byte to wiper new position	-	1.5	-	µs
$t_{ShdnRec}$	DCP Recall Time from Shutdown Mode	SCL rising edge of the acknowledge bit after ACR data byte to wiper recalled position and RH connection	-	1.5	-	µs
V_{CC}, V_{LOGIC} Ramp (Note 20)	V_{CC} , V_{LOGIC} Ramp Rate	Ramp monotonic at any level	**0.01**	-	**50**	V/ms

Serial Interface Specification

For SCL, SDA, A0, A1 unless otherwise noted.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN (Note 19)	TYP (Note 7)	MAX (Note 19)	UNITS
V_{IL}	Input LOW Voltage		-0.3		0.3 x V_{LOGIC}	V

Serial Interface Specification For SCL, SDA, A0, A1 unless otherwise noted. (Continued)

SYMBOL	PARAMETER	TEST CONDITIONS	MIN (Note 19)	TYP (Note 7)	MAX (Note 19)	UNITS
V_{IH}	Input HIGH Voltage	-	0.7 x V_{LOGIC}	-	V_{LOGIC} + 0.3	V
Hysteresis	SDA and SCL Input Buffer Hysteresis	V_{LOGIC} > 2V	0.05 x V_{LOGIC}	-	-	V
		V_{LOGIC} < 2V	0.1 x V_{LOGIC}	-	-	V
V_{OL}	SDA Output Buffer LOW Voltage	I_{OL} = 3mA, V_{LOGIC} > 2V	0	-	0.4	V
		I_{OL} = 1.5mA, V_{LOGIC} < 2V	-	-	0.2 x V_{LOGIC}	V
C_{pin}	SDA, SCL Pin Capacitance	-	-	10		pF
f_{SCL}	SCL Frequency	-	-	-	400	kHz
t_{sp}	Pulse Width Suppression Time at SDA and SCL Inputs	Any pulse narrower than the max spec is suppressed	-	-	50	ns
t_{AA}	SCL Falling Edge to SDA Output Data Valid	SCL falling edge crossing 30% of V_{LOGIC}, until SDA exits the 30% to 70% of V_{LOGIC} window	-	-	900	ns
t_{BUF}	Time the Bus Must be Free Before the Start of a New Transmission	SDA crossing 70% of V_{LOGIC} during a STOP condition, to SDA crossing 70% of V_{LOGIC} during the following START condition	1300	-	-	ns
t_{LOW}	Clock LOW Time	Measured at the 30% of V_{LOGIC} crossing	1300	-	-	ns
t_{HIGH}	Clock HIGH Time	Measured at the 70% of V_{LOGIC} crossing	600	-	-	ns
$t_{SU:STA}$	START Condition Set-up Time	SCL rising edge to SDA falling edge; both crossing 70% of V_{LOGIC}	600	-	-	ns
$t_{HD:STA}$	START Condition Hold Time	From SDA falling edge crossing 30% of V_{LOGIC} to SCL falling edge crossing 70% of V_{LOGIC}	600	-	-	ns
$t_{SU:DAT}$	Input Data Set-up Time	From SDA exiting the 30% to 70% of V_{LOGIC} window, to SCL rising edge crossing 30% of V_{LOGIC}	100	-	-	ns
$t_{HD:DAT}$	Input Data Hold Time	From SCL falling edge crossing 70% of V_{CC} to SDA entering the 30% to 70% of V_{LOGIC} window	0	-	-	ns
$t_{SU:STO}$	STOP Condition Set-up Time	From SCL rising edge crossing 70% of V_{LOGIC}, to SDA rising edge crossing 30% of V_{LOGIC}	600	-	-	ns
$t_{HD:STO}$	STOP Condition Hold Time for Read or Write	From SDA rising edge to SCL falling edge; both crossing 70% of V_{LOGIC}	1300	-	-	ns
t_{DH}	Output Data Hold Time	From SCL falling edge crossing 30% of V_{LOGIC}, until SDA enters the 30% to 70% of V_{LOGIC} window. I_{OL} = 3mA, V_{LOGIC} > 2V. I_{OL} = 0.5mA, V_{LOGIC} < 2V	0	-	-	ns
t_R	SDA and SCL Rise Time	From 30% to 70% of V_{LOGIC}	20 + 0.1 x Cb	-	250	ns
t_F	SDA and SCL Fall Time	From 70% to 30% of V_{LOGIC}	20 + 0.1 x Cb	-	250	ns

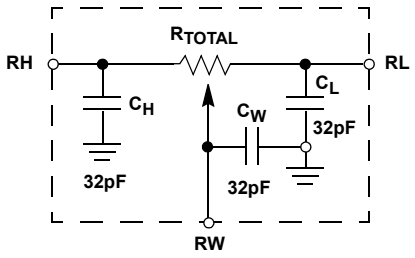
Serial Interface Specification For SCL, SDA, A0, A1 unless otherwise noted. (Continued)

SYMBOL	PARAMETER	TEST CONDITIONS	MIN (Note 19)	TYP (Note 7)	MAX (Note 19)	UNITS
Cb	Capacitive Loading of SDA or SCL	Total on-chip and off-chip	10	-	400	pF
$t_{SU:A}$	A1, A0 Set-up Time	Before START condition	600	-	-	ns
$t_{HD:A}$	A1, A0 Hold Time	After STOP condition	600	-	-	ns

NOTES:

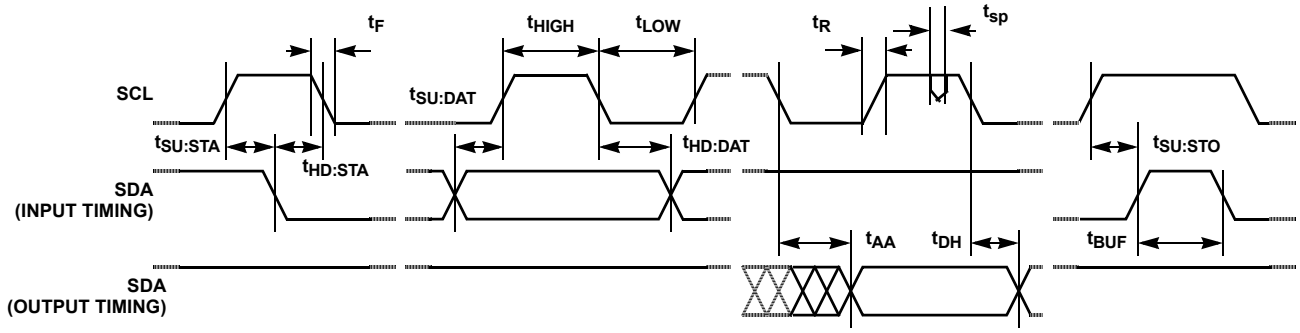
7. Typical values are for T_A = +25°C and 3.3V supply voltages.
8. LSB = $[V(RW)_{127} - V(RW)_0]/127$. $V(RW)_{127}$ and $V(RW)_0$ are V(RW) for the DCP register set to 7F hex and 00 hex respectively. LSB is the incremental voltage when changing from one tap to an adjacent tap.
9. ZS error = $V(RW)_0$/LSB.
10. FS error = $[V(RW)_{127} - V_{CC}]$/LSB.
11. DNL = $[V(RW)_i - V(RW)_{i-1}]$/LSB-1, for i = 1 to 127. i is the DCP register setting.
12. INL = $[V(RW)_i - i \bullet LSB - V(RW)_0]$/LSB for i = 1 to 127.
13. $TC_V = \frac{Max(V(RW)_i) - Min(V(RW)_i)}{V(RW_i(+25°C))} \times \frac{10^6}{+165°C}$ For i = 16 to 127 decimal, T = -40°C to +125°C. Max( ) is the maximum value of the wiper voltage and Min( ) is the minimum value of the wiper voltage over the temperature range.
14. MI = $|RW_{127} - RW_0|/127$. MI is a minimum increment. RW_{127} and RW_0 are the measured resistances for the DCP register set to 7F hex and 00 hex respectively.
15. Roffset = RW_0/MI, when measuring between RW and RL.
    Roffset = RW_{127}/MI, when measuring between RW and RH.
16. RDNL = $(RW_i - RW_{i-1})$/MI -1, for i = 8 to 127.
17. RINL = $[RW_i - (MI \bullet i) - RW_0]$/MI, for i = 8 to 127.
18. $TC_R = \frac{[Max(Ri) - Min(Ri)]}{Ri(+25°C)} \times \frac{10^6}{+165°C}$ For i = 8 to 127, T = -40°C to +125°C. Max( ) is the maximum value of the resistance and Min( ) is the minimum value of the resistance over the temperature range.
19. Compliance to datasheet limits is assured by one or more methods: production test, characterization and/or design.
20. It is preferable to ramp up both the V_{LOGIC} and the V_{CC} supplies at the same time, and wait for V_{CC} to be turned ramped up to start I^2C communication. Otherwise, with ramping up only V_{LOGIC} I^2C communication is not possible.

DCP Macro Model

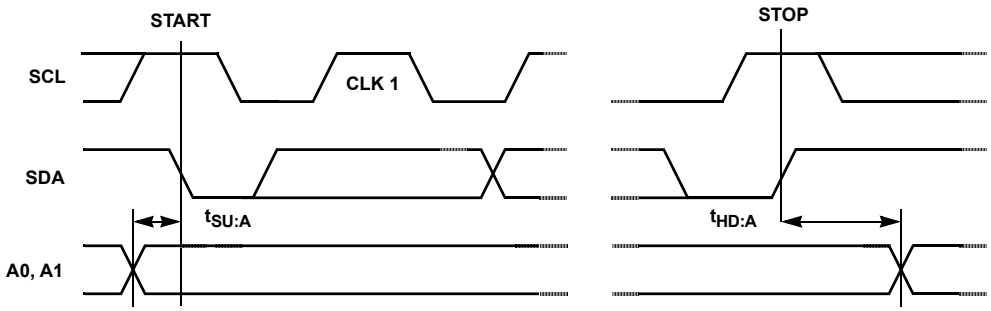


Timing Diagrams

SDA vs SCL Timing



A0 and A1 Pin Timing



Typical Performance Curves

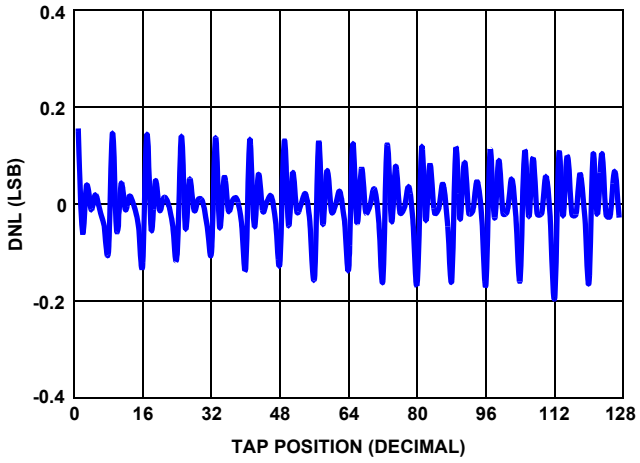


FIGURE 3. 10k DNL vs TAP POSITION, V_{CC} = 5V

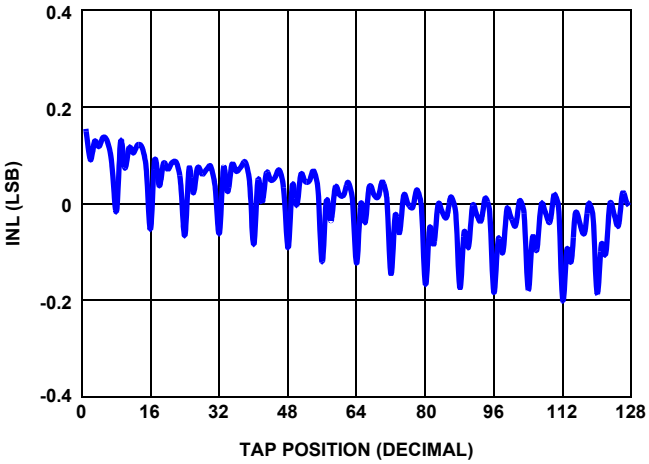


FIGURE 4. 10k INL vs TAP POSITION, V_{CC} = 5V

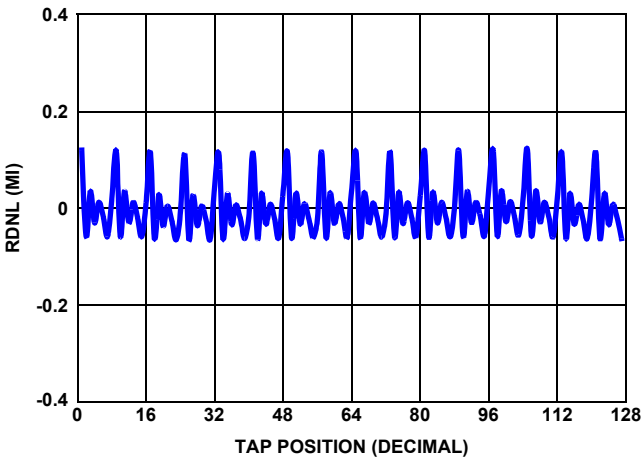


FIGURE 5. 10k RDNL vs TAP POSITION, V_{CC} = 5V

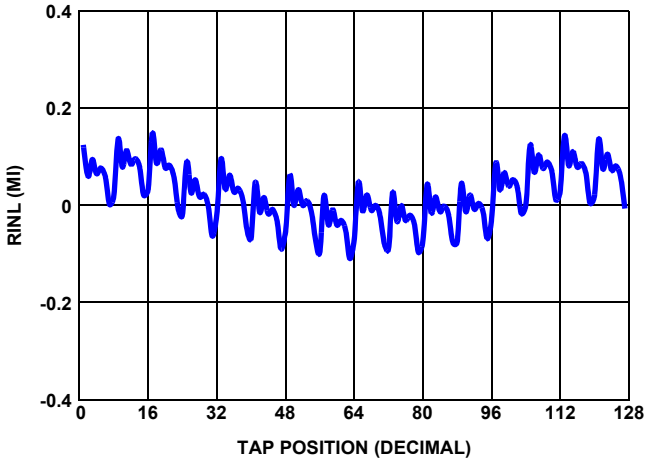


FIGURE 6. 10k RINL vs TAP POSITION, V_{CC} = 5V

Typical Performance Curves (Continued)

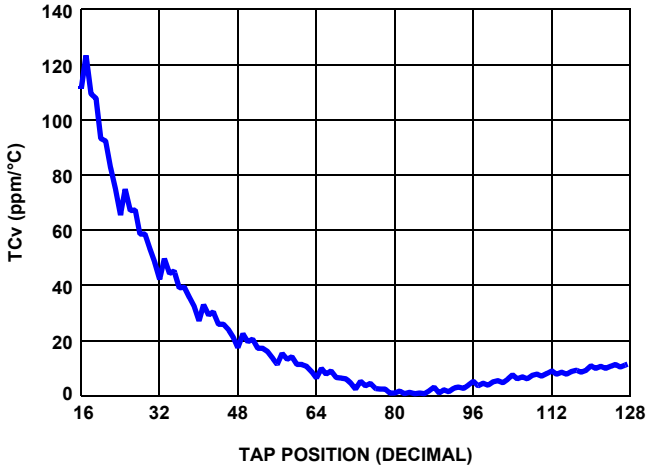


FIGURE 7. 10k TCv vs TAP POSITION

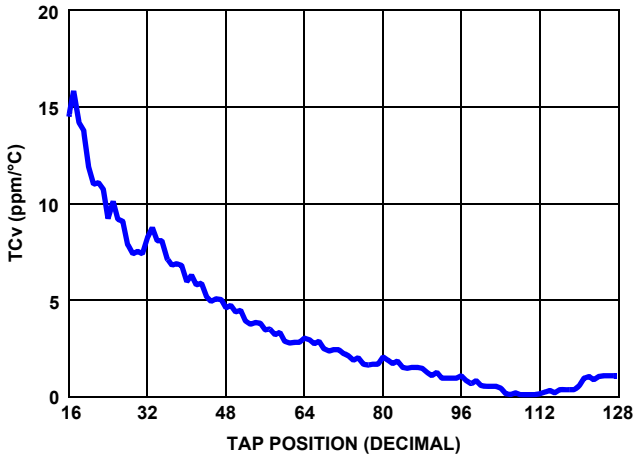


FIGURE 8. 100k TCv vs TAP POSITION

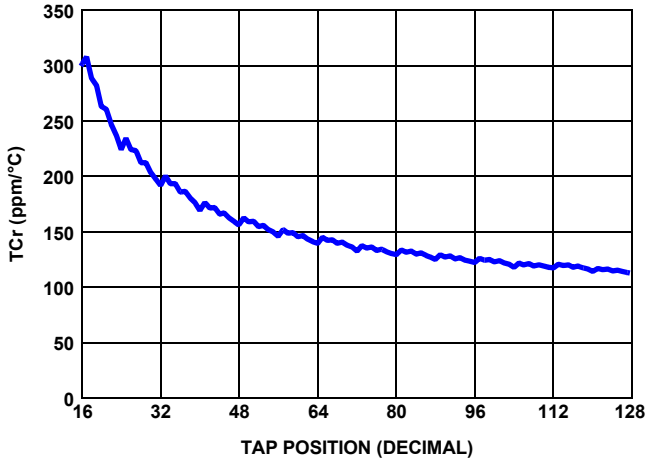


FIGURE 9. 10k TCr vs TAP POSITION

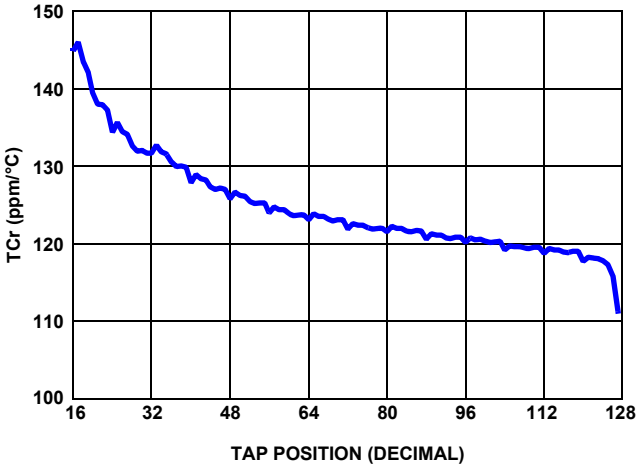


FIGURE 10. 100k TCr vs TAP POSITION

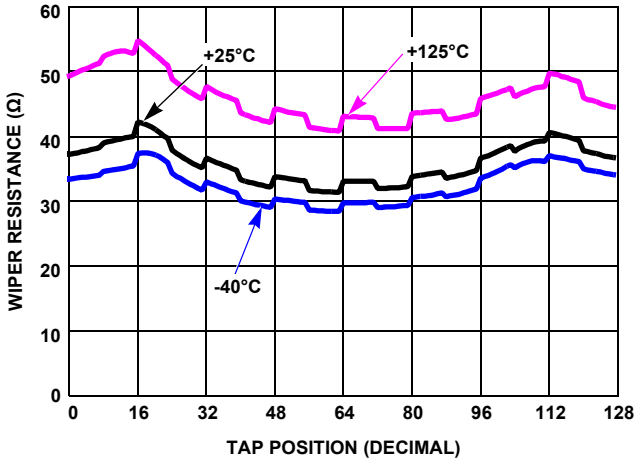


FIGURE 11. 10k WIPER RESISTANCE vs TAP POSITION, V_{CC} = 5V

Typical Performance Curves (Continued)

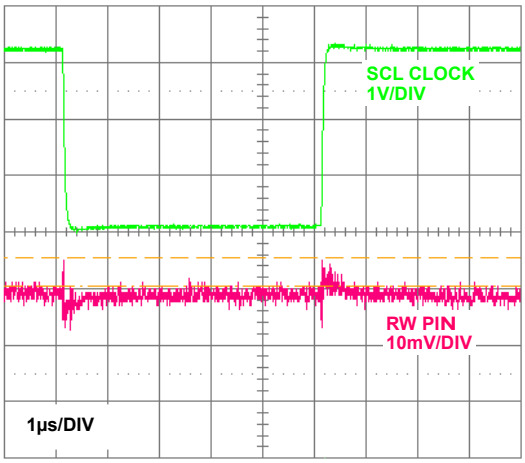


FIGURE 12. WIPER DIGITAL FEED-THROUGH

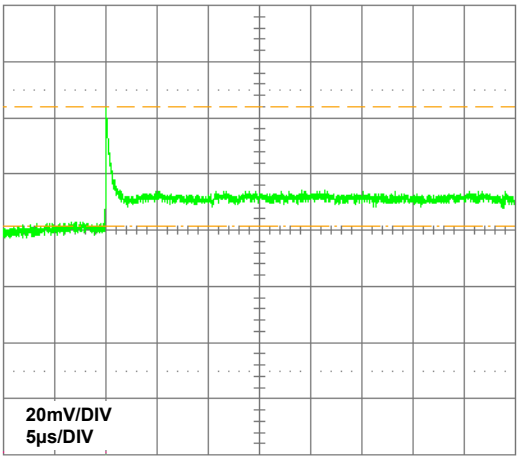


FIGURE 13. WIPER TRANSITION GLITCH

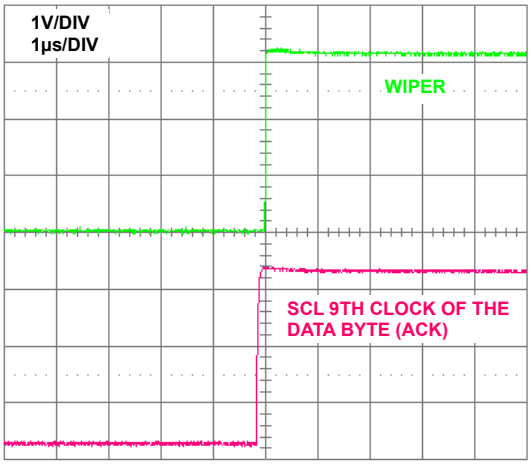


FIGURE 14. WIPER LARGE SIGNAL SETTLING TIME

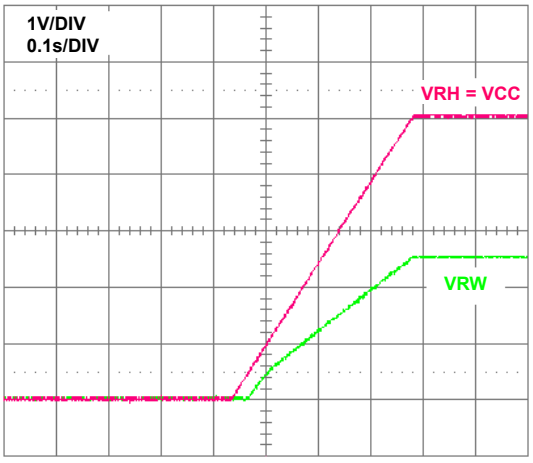


FIGURE 15. POWER-ON START-UP IN VOLTAGE DIVIDER MODE

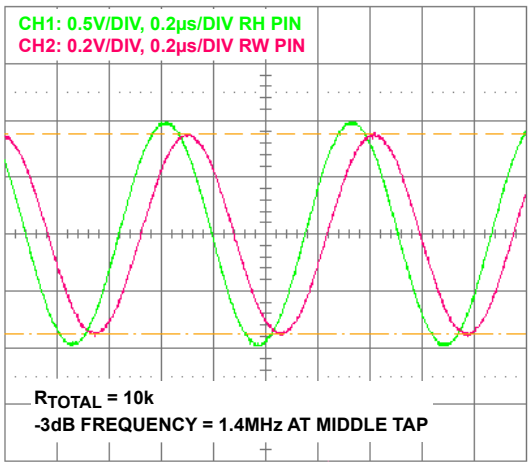


FIGURE 16. 10k -3dB CUT OFF FREQUENCY

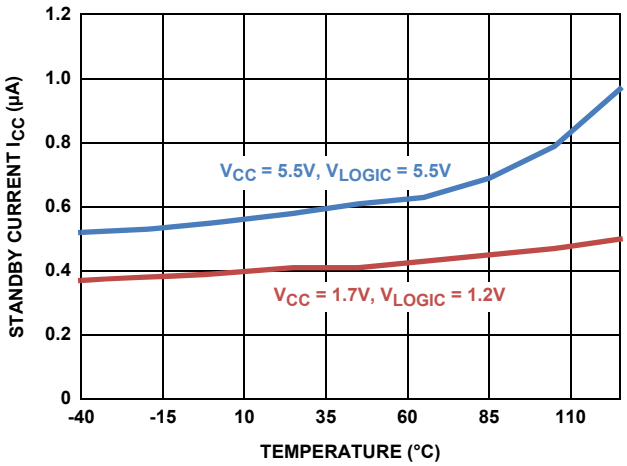


FIGURE 17. STANDBY CURRENT vs TEMPERATURE

Functional Pin Descriptions

Potentiometers Pins

RH AND RL

The high (R_H) and low (R_L) terminals of the ISL23318 are equivalent to the fixed terminals of a mechanical potentiometer. R_H and R_L are referenced to the relative position of the wiper and not the voltage potential on the terminals. With WR set to 127 decimal, the wiper will be closest to R_H, and with the WR set to 0, the wiper is closest to R_L.

RW

RW is the wiper terminal, and it is equivalent to the movable terminal of a mechanical potentiometer. The position of the wiper within the array is determined by the WR register.

Bus Interface Pins

SERIAL DATA INPUT/OUTPUT (SDA)

The SDA is a bidirectional serial data input/output pin for I^2C interface. It receives device address, wiper address and data from an I^2C external master device at the rising edge of the serial clock SCL, and it shifts out data after each falling edge of the serial clock.

SDA requires an external pull-up resistor, since it is an open drain input/output.

SERIAL CLOCK (SCL)

This input is the serial clock of the I^2C serial interface. SCL requires an external pull-up resistor, since a master is an open drain output.

DEVICE ADDRESS (A1, A0)

The address inputs are used to set the least significant 2 bits of the 7-bit I^2C interface slave address. A match in the slave address serial data stream must match with the Address input pins in order to initiate communication with the ISL23318. A maximum of four ISL23318 devices may occupy the I^2C serial bus (see Table 3).

V_{LOGIC}

This is an input pin that supplies internal level translator for serial bus operation from 1.2V to 5.5V.

Principles of Operation

The ISL23318 is an integrated circuit incorporating one DCP with its associated registers and an I^2C serial interface providing direct communication between a host and the potentiometer. The resistor array is comprised of individual resistors connected in series. At either end of the array and between each resistor is an electronic switch that transfers the potential at that point to the wiper.

The electronic switches on the device operate in a “make-before-break” mode when the wiper changes tap positions.

Voltage at any DCP pins, R_H, R_L or R_W, should not exceed V_{CC} level at any conditions during power-up and normal operation.

The V_{LOGIC} pin needs to be connected to the I^2C bus supply which allows reliable communication with the wide range of microcontrollers and independent of the V_{CC} level. This is extremely important in systems where the master supply has lower levels than DCP analog supply.

DCP Description

The DCP is implemented with a combination of resistor elements and CMOS switches. The physical ends of each DCP are equivalent to the fixed terminals of a mechanical potentiometer (RH and RL pins). The RW pin of the DCP is connected to intermediate nodes, and is equivalent to the wiper terminal of a mechanical potentiometer. The position of the wiper terminal within the DCP is controlled by a 7-bit volatile Wiper Register (WR). When the WR of a DCP contains all zeroes (WR[7:0] = 00h), its wiper terminal (RW) is closest to its “Low” terminal (RL). When the WR register of a DCP contains all ones (WR[7:0] = 7Fh), its wiper terminal (RW) is closest to its “High” terminal (RH). As the value of the WR increases from all zeroes (0) to 0111 1111b (127 decimal), the wiper moves monotonically from the position closest to RL to the position closest to RH. At the same time, the resistance between RW and RL increases monotonically, while the resistance between RH and RW decreases monotonically.

While the ISL23318 is being powered up, the WR is reset to 40h (64 decimal), which locates RW roughly at the center between R_L and R_H.

The WR can be read or written to directly using the I^2C serial interface as described in the following sections.

Memory Description

The ISL23318 contains two volatile 8-bit registers: Wiper Register (WR) and Access Control Register (ACR). The memory map of ISL23318 is shown in Table 1. The Wiper Register (WR) at address 0 contains current wiper position. The Access Control Register (ACR) at address 10h contains information and control bits described in Table 2.

TABLE 1. MEMORY MAP

ADDRESS (hex)	VOLATILE REGISTER NAME	DEFAULT SETTING (hex)
10	ACR	40
0	WR	40

TABLE 2. ACCESS CONTROL REGISTER (ACR)

BIT #	7	6	5	4	3	2	1	0
NAME/ VALUE	0	$\overline{SHDN}$	0	0	0	0	0	0

Shutdown Function

The $\overline{SHDN}$ bit (ACR[6]) disables or enables shutdown mode for all DCP channels simultaneously. When this bit is 0, i.e., DCP is forced to end-to-end open circuit and RW is connected to RL through a 2kΩ serial resistor as shown in Figure 18. Default value of the $\overline{SHDN}$ bit is 1

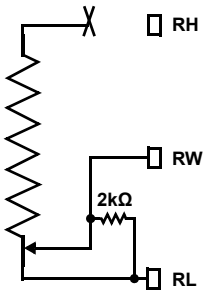


FIGURE 18. DCP CONNECTION IN SHUTDOWN MODE

In the shutdown mode, the RW terminal is shorted to the RL terminal with around 2kΩ resistance as shown in Figure 18. When the device enters shutdown, all current DCP WR settings are maintained. When the device exits shutdown, the wipers will return to the previous WR settings after a short settling time (see Figure 19).

In shutdown mode, if there is a glitch on the power supply which causes it to drop below 1.3V for more than 0.2µs to 0.4µs, the wipers will be RESET to their mid position. This is done to avoid an undefined state at the wiper outputs.

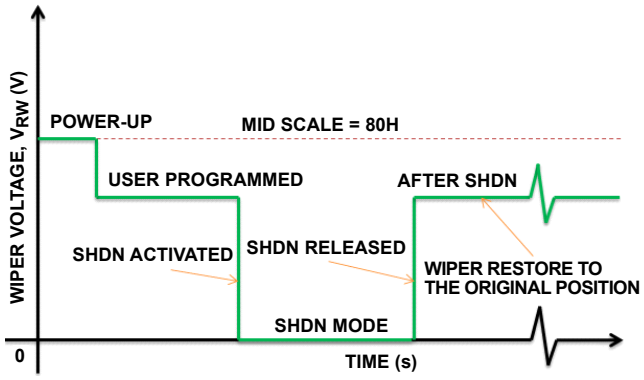


FIGURE 19. SHUTDOWN MODE WIPER RESPONSE

I²C Serial Interface

The ISL23318 supports an I²C bidirectional bus oriented protocol. The protocol defines any device that sends data onto the bus as a transmitter and the receiving device as the receiver. The device controlling the transfer is a master and the device being controlled is the slave. The master always initiates data transfers and provides the clock for both transmit and receive operations. Therefore, the ISL23318 operates as a slave device in all applications.

All communication over the I²C interface is conducted by sending the MSB of each byte of data first.

Protocol Conventions

Data states on the SDA line must change only during SCL LOW periods. SDA state changes during SCL HIGH are reserved for indicating START and STOP conditions (see Figure 20). On power-up of the ISL23318, the SDA pin is in the input mode.

All I²C interface operations must begin with a START condition, which is a HIGH-to-LOW transition of SDA while SCL is HIGH. The ISL23318 continuously monitors the SDA and SCL lines for the START condition and does not respond to any command until this condition is met (see Figure 20). A START condition is ignored during the power-up of the device.

All I²C interface operations must be terminated by a STOP condition, which is a LOW to HIGH transition of SDA while SCL is HIGH (see Figure 20). A STOP condition at the end of a read operation or at the end of a write operation places the device in its standby mode.

An ACK (Acknowledge) is a software convention used to indicate a successful data transfer. The transmitting device, either master or slave, releases the SDA bus after transmitting eight bits. During the ninth clock cycle, the receiver pulls the SDA line LOW to acknowledge the reception of the eight bits of data (see Figure 21).

The ISL23318 responds with an ACK after recognition of a START condition followed by a valid Identification Byte, and once again after successful receipt of an Address Byte. The ISL23318 also responds with an ACK after receiving a Data Byte of a write operation. The master must respond with an ACK after receiving a Data Byte of a read operation.

A valid Identification Byte contains 10100 as the five MSBs, and the following two bits matching the logic values present at pins A1 and A0. The LSB is the Read/$\overline{Write}$ bit. Its value is “1” for a Read operation and “0” for a Write operation (see Table 3).

TABLE 3. IDENTIFICATION BYTE FORMAT

					LOGIC VALUES AT PINS A1 AND A0, RESPECTIVELY		
1	0	1	0	0	A1	A0	R/$\overline{W}$
(MSB)							(LSB)

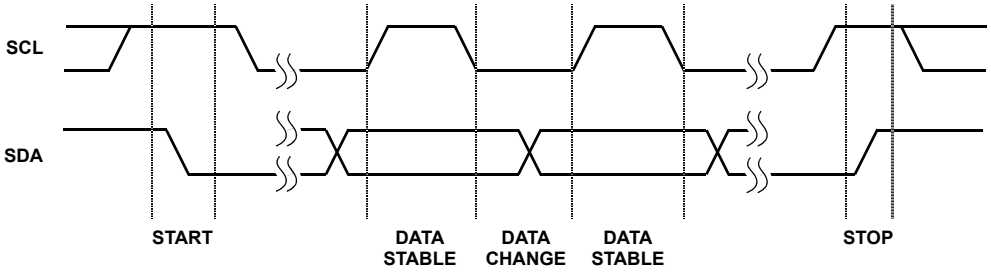


FIGURE 20. VALID DATA CHANGES, START AND STOP CONDITIONS

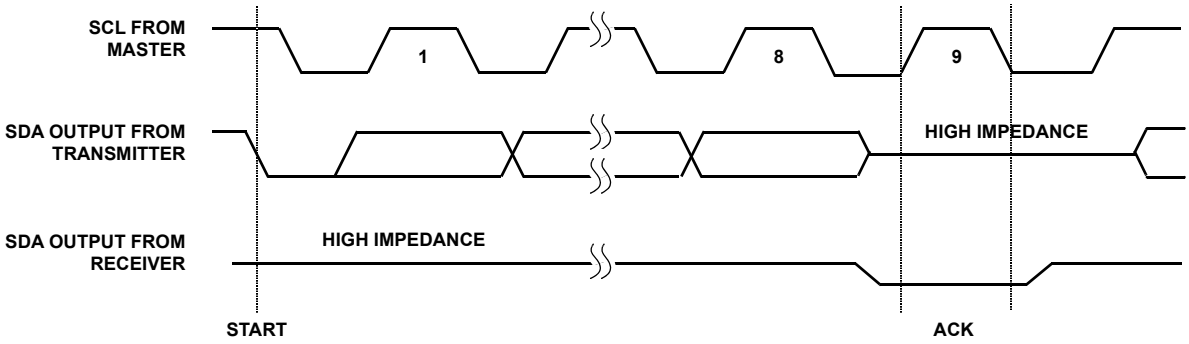


FIGURE 21. ACKNOWLEDGE RESPONSE FROM RECEIVER

Write Operation

A Write operation requires a START condition, followed by a valid Identification Byte, a valid Address Byte, a Data Byte, and a STOP condition. After each of the three bytes, the ISL23318 responds with an ACK. The data is transferred from I^2C block to the corresponding register at the 9th clock of the data byte and device enters its standby state (see Figures 21 and 22).

Read Operation

A Read operation consists of a three byte instruction followed by one or more Data Bytes (see Figure 23). The master initiates the operation issuing the following sequence: a START, the Identification byte with the R/$\overline{W}$ bit set to “0”, an Address Byte, a second START, and a second Identification byte with the R/$\overline{W}$ bit set to “1”. After each of the three bytes, the ISL23318 responds with an ACK; then the ISL23318 transmits Data Byte. The master terminates the read operation issuing a NACK ($\overline{ACK}$) and a STOP condition following the last bit of the last Data Byte (see Figure 23).

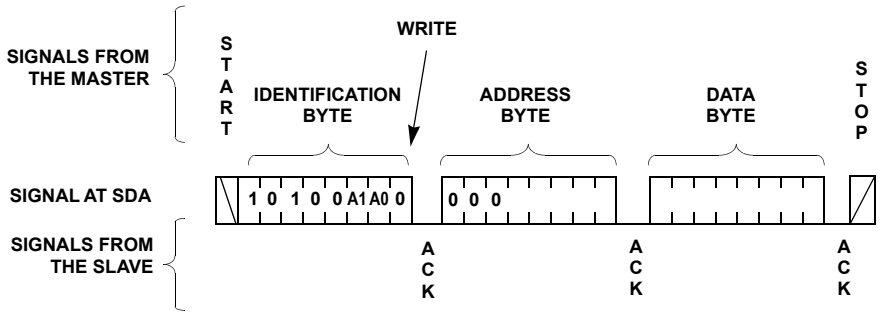


FIGURE 22. BYTE WRITE SEQUENCE

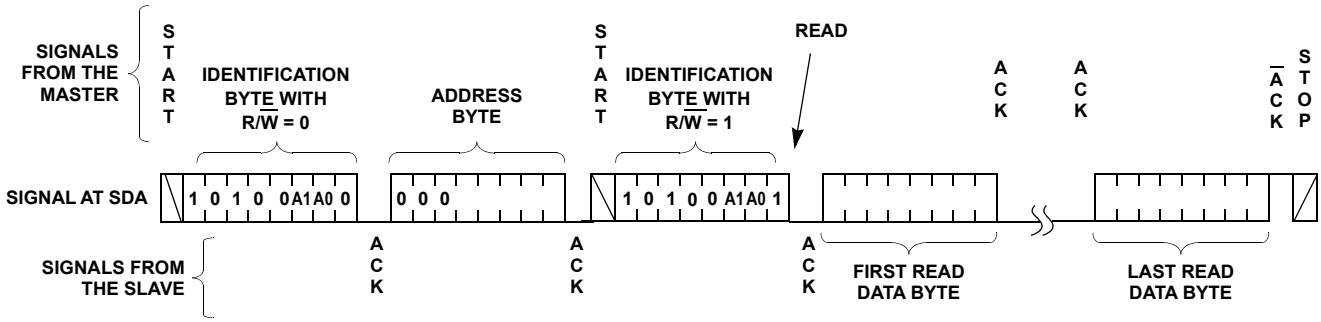


FIGURE 23. READ SEQUENCE

Applications Information

V_{LOGIC} Requirements

It is recommended to keep V_{LOGIC} powered all the time during normal operation. In a case where turning V_{LOGIC} OFF is necessary, it is recommended to ground the V_{LOGIC} pin of the ISL23318. Grounding the V_{LOGIC} pin or both V_{LOGIC} and V_{CC} does not affect other devices on the same bus. It is good practice to put a 1µF cap in parallel to 0.1µF as close to the V_{LOGIC} pin as possible.

V_{CC} Requirements and Placement

It is recommended to put a 1µF capacitor in parallel with 0.1µF decoupling capacitor close to the V_{CC} pin.

I^2C Communication Requirements

Renesas recommends ramping up V_{CC} and V_{LOGIC} simultaneously to ensure correct device operation.

In applications where V_{LOGIC} must ramp up before V_{CC}, I^2C communication remains inactive until V_{CC} has been fully established. This is because the release of the SDA line depends on V_{CC} during power-up.

For applications that require instant I^2C communication without V_{CC} being present, the hardware workaround shown in Figure 24 is available.

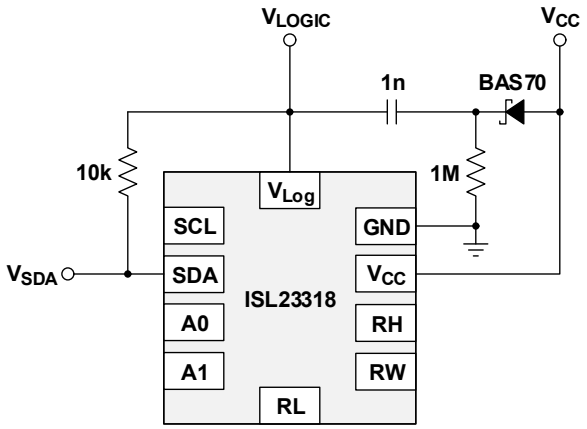


FIGURE 24. DESIGN FOR HARDWARE WORK AROUND

For applications where a hardware workaround is not feasible, a software solution must be applied. This software solution introduces a 50ms delay before I^2C communication following the completion of the V_{CC} ramp-up.

Wiper Transition

When stepping up through each tap in voltage divider mode, some tap transition points can result in noticeable voltage transients, or overshoot/undershoot, resulting from the sudden transition from a very low impedance “make” to a much higher impedance “break” within a short period of time (<1µs). There are several code transitions such as 0Fh to 10h, 1Fh to 20h,..., 7Eh to 7Fh, which have higher transient glitch. Note that all switching transients will settle well within the settling time as stated in the datasheet. A small capacitor can be added externally to reduce the amplitude of these voltage transients. However, that will also reduce the useful bandwidth of the circuit, thus may not be a good solution for some applications. It may be a good idea, in that case, to use fast amplifiers in a signal chain for fast recovery.

Revision History

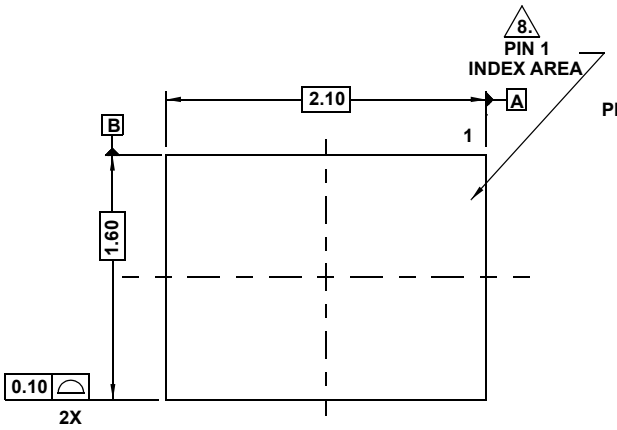
The revision history provided is for informational purposes only and is believed to be accurate, but not warranted. Please go to web to make sure you have the latest Rev.

DATE	REVISION	CHANGE
Mar 5, 2024	1.00	Removed U option information. Added I^2C Communication Requirements section. Updated Ordering information table. Removed Products section. Updated M10.118 to the latest revision, changes are as follows: -Added land pattern -Corrected typo in the side view 1 updating package thickness tolerance from ±010 to ±0.10.
Jul 26, 2011	0.00	Initial Release

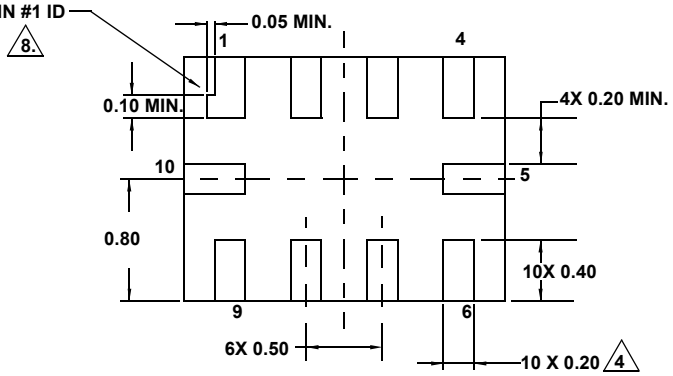
Package Outline Drawings

For the most recent package outline drawing, see L10.2.1x1.6A.

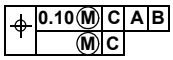
L10.2.1x1.6A
10 Lead Ultra Thin Quad Flat No-Lead Plastic Package
Rev 5, 3/10

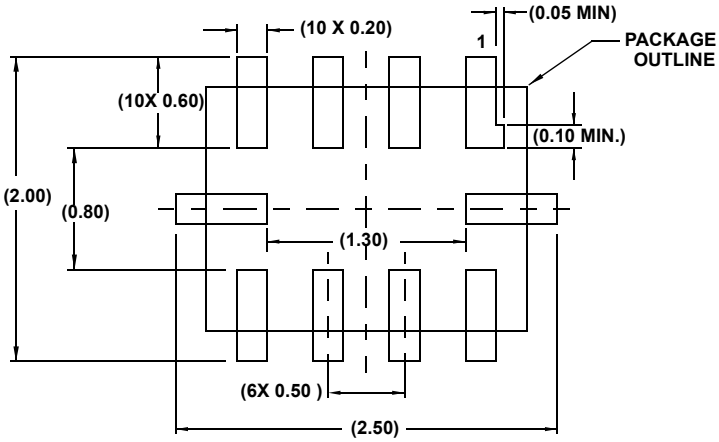


TOP VIEW

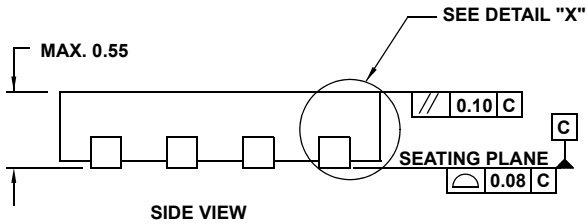


BOTTOM VIEW

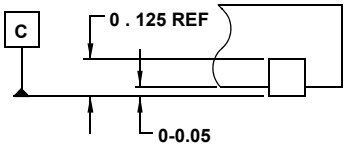




TYPICAL RECOMMENDED LAND PATTERN



SIDE VIEW



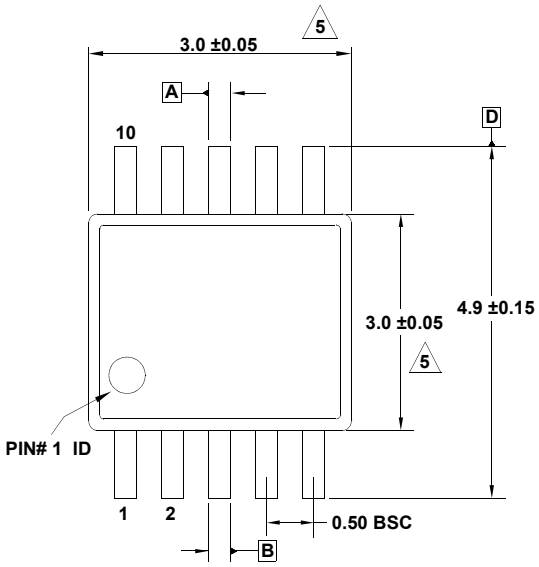
DETAIL "X"

NOTES:

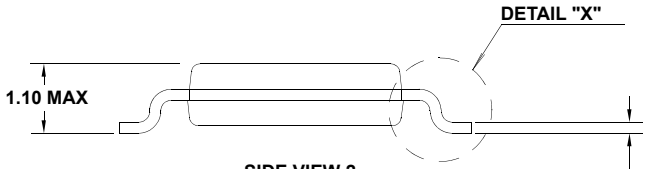
1. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
2. All Dimensions are in millimeters. Angles are in degrees. Dimensions in ( ) for Reference Only.
3. Unless otherwise specified, tolerance : Decimal ± 0.05
4. Lead width dimension applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
5. Maximum package warpage is 0.05mm.
6. Maximum allowable burrs is 0.076mm in all directions.
7. Same as JEDEC MO-255UABD except:
   No lead-pull-back, MIN. Package thickness = 0.45 not 0.50mm
   Lead Length dim. = 0.45mm max. not 0.42mm.
8. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.

For the most recent package outline drawing, see M10.118.

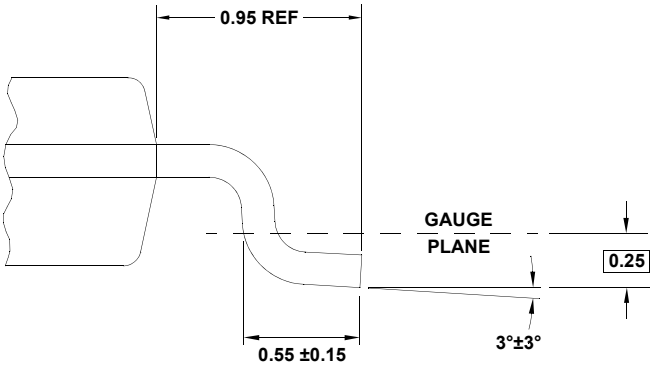
M10.118
10 Lead Mini Small Outline Plastic Package
Rev 2, 5/2021



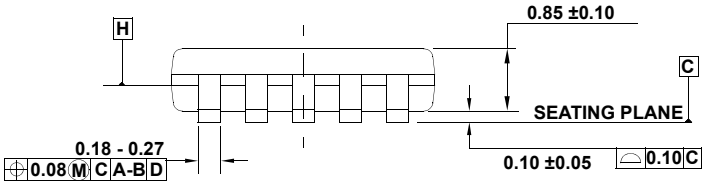
TOP VIEW



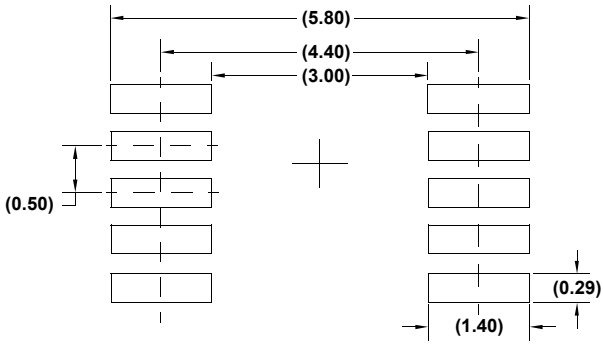
SIDE VIEW 2



DETAIL "X"



SIDE VIEW 1



TYPICAL RECOMMENDED LAND PATTERN

NOTES:

1. Dimensions are in millimeters.
2. Dimensioning and tolerancing conform to JEDEC MO-187-BA and AMSEY14.5m-1994.
3. Plastic or metal protrusions of 0.15mm max per side are not included.
4. Plastic interlead protrusions of 0.15mm max per side are not included.
5. Dimensions are measured at Datum Plane "H".
6. Dimensions in ( ) are for reference only.

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